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PRESS RELEASE

(For Immediate Release)

SINGAPORE WINDSOR TO TAKE 51% STAKE IN ADVANCED TECHNOLOGY FIRM, TAIWAN 3D- CIRCUIT INDUSTRIAL CO. LTD

- *The Group via its investment holding company will take a 51% interest in Taiwanese firm , Taiwan 3D-Circuit Industrial Co. Ltd, which specialises in research & development, manufacture and sales of 3D-MID (three dimensional – moulded interconnect devices) related products*
- *3D-MID technology currently acts as a complement to printed circuit boards (PCB) as it embeds electronic circuitry onto an injection moulded plastic layer, thereby enabling mechanical and electrical functions to be integrated onto a single component*
- *Latest move is aimed at extending the Group's technology base and moving up the value chain to engage with higher tier customers in the electronics industry*
- *The acquisition shall be via cash injection of an estimated S\$1.2 million, to be funded from proceeds of the Group's initial public offering.*

SINGAPORE, 28 May 2007 – Mainboard-listed Singapore Windsor Holdings Limited (“Singapore Windsor” “新加坡荣华控股有限公司” and together with its subsidiaries, the “Group”), a manufacturer of quality moulds and provider of related support services, today announced the purchase of 51% interest in Taiwan 3D-Circuit Industrial Co. Ltd, a firm based in Taiwan specialising in the research and development, manufacture and sales of 3D Module Interconnect Devices related products.

“3D-MID” (or Three Dimensional Moulded Interconnect Devices) refers to a technology where plastic mouldings incorporate, or have on their surface, an integrated circuit pattern. As such they represent the fusion of mechanical and electrical functionality into one integrated component.

Traditional printed circuit boards (“PCB”) are two-dimensional modules that typically accommodate electronic components on one or both sides. MIDs possess enormous potential for technical innovation and rationalization and are substantially more environmentally friendly than conventional PCBs, which they are intended to supplement but not replace.

The Rationale

Commenting on the rationale of this latest move, Mr Michael Chung (“钟华生”) Chief Executive Officer, Singapore Windsor Holdings Limited, said ***“We are excited by this latest development as this acquisition is meant to move Singapore Windsor up the value chain and to develop closer linkages with higher tier customers in the electronics industry.”***

According to a report on MID technology by PRIME Faraday partnership, consumer demands for smaller multifunctional devices, such as mobile phones, PDA’s and mobile computers are prime targets for the application of MID technology. This is driven by the potential to integrate electrical functions into in-built mechanical devices such as flip-top lids, screen hinges, miniature keyboards, and screen pointers becomes a key way to save space and increase functionality.

“While this technology is still new to some electronics manufacturer, we believe the pace of acceptance and growth of 3D-MID technology will hasten because of increasing complexity and sophistication of electronic devices. This is an exciting and long term development for the Group.” Mr Chung added.

The Group believes that 3D-MID will remain a complementary technology to traditional PCB which will still be the mainstay component in most electronics products in the foreseeable future.

“We expect the 3D MID initiative will be a longer term contributor to the Group’s performance and expect to see some contribution to the Group’s bottom line in FY2009 onwards.” Mr Michael Chung concluded.

The purchase of 51% stake in Taiwan 3D-Circuit Industrial Co. Ltd shall be completed via the cash injection of an estimated S\$1.2 million, to be funded from the proceeds of the Group’s initial public offering. The Group had announced on 22 May 2007 that it had incorporated a company, Audika Ltd (“Audika”), where it will take a 51% stake and operate a special steel production plant in Shaoguan, Guangdong Province, People’s Republic of China (“PRC”). Further announcements will be made upon the signing of the relevant venture agreement.

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Issued on behalf of Singapore Windsor Holdings Limited by

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About Singapore Windsor Holdings Limited

The origins of our Group can be tracked back to early 1986 when our founders Michael Chung and Hugo Chung established a partnership in Hong Kong to supply PCB punching moulds to PCB manufacturers based in the PRC. Since then, we have expanded our service range to include die-casting and plastic injection mould base manufacturing as well as electroplating and punching services to our customers who in turn service end-customers that manufacture telecommunication devices, automobile electronics devices and consumer electronics products.

Our strategy is to provide quick turnaround time in the production of quality moulds and the provision of support services to our customers based mainly in Guangdong and Jiangsu provinces. Our manufacturing facilities are therefore located within a two hour transport range in order for us to support our customers by reducing their time required to market their new products.

Note :

This release may contain predictions, estimates or other information that may be considered forward-looking statements. Actual results may differ materially from those currently expected because of a number of factors. These factors include (without limitation) changes in general industry and economic conditions, interest rate

movements, cost of capital and capital availability, competition from other companies and venues for sale / manufacture / distribution of goods and services, shift in customer demands, changes in operating expenses, including employee wages and raw material prices, governmental and public policy changes, social and political turmoil and major health concerns. You are cautioned not to place undue reliance on these forward-looking statements, which are based on current view of management on future events. The Company undertakes no obligation to publicly update or revise any forward looking statements, whether as a result of new information, future events or otherwise, except as required by law.